



## 特点

- \* 外形尺寸: 61.0 × 57.9 × 12.7 mm
- \* 工业标准半砖封装和引脚
- \* 高效率、高功率密度
- \* 基板工作温度 100℃

## Features

- \* Size: 2.40 × 2.28 × 0.50 inch
- \* Industry Standard Half-Brick Package and Footprint
- \* High Efficiency, High Power Density
- \* 100℃ Baseplate Operation

输入特性 (Input)		注释 (Notes and Conditions)	
输入电压范围 (Input Voltage Range)			
标称 (Nominal)	48Vdc	36~72Vdc	80Vdc Max
标称 (Nominal)	24Vdc	18~36Vdc	40Vdc Max
输入欠压保护 (Input Undervoltage Protection) <36Vdc (IN:48Vdc); <18Vdc (IN:24Vdc)			
遥控功能 (Remote On/Off Function)			
1) 正逻辑 (Positive Logic)	开启 (On)	高电平 (2.5 ~ 18Vdc) 或悬空 (High Level or Open Circuit)	相对于 -Vin (Reference to -Vin)
	关闭 (Off)	低电平 (<1.4Vdc) 或与 -Vin 短接 (Low Level or Connect to -Vin)	
2) 负逻辑 (Negative Logic)	开启 (On)	低电平 (<0.4Vdc) 或与 -Vin 短接 (Low Level or Connect to -Vin)	相对于 -Vin (Reference to -Vin) 型号后加后缀 "-L"
	关闭 (Off)	高电平 (1.4 ~ 18Vdc) 或悬空 (High Level or Open Circuit)	(Adding the Suffix "-L" to the Model Number)
输出特性 (Output)		注释 (Notes and Conditions)	
输出电压精度 (Voltage Set-Point Accuracy)	± 1%	Vinom and Ionom	
输出电压调节范围 (Output Voltage Trim Range)	± 10%		
源效应 (Line Regulation)	± 0.2%Vo	Vimin~Vimax, Ionom	
负载效应 (Load Regulation)	± 0.5%Vo	10%~100%Ionom, Vinom	
输出过压保护 (Output Overvoltage Protection)	120%~140%Vo	Self Recovering	
输出过流保护点 (Current Limit Threshold Range)	110%~150%Io		
短路保护 (Short-Circuit Protection)	连续可恢复 (Continuous, Automatic Recovery)		
瞬态响应 (Dynamic Response)			
过冲幅度 (Peak Deviation)	± 5%Vo	25%-50%-25% of Ionom	
恢复时间 (Settling Time)	200 μs	and 50%-75%-50% of Ionom	
一般特性 (General)		注释 (Notes and Conditions)	
温度系数 (Temperature Coefficient)	± 0.02%/℃		
隔离电压 (Isolation Voltage)			
输入与输出 (Input-Output)	1000Vdc 1min		
输入与外壳 (Input-Case)	700Vdc 1min		
输出与外壳 (Output-Case)	500Vdc 1min		
工作基板温度 (Operating Baseplate Temperature)	-25℃~+100℃		
贮存温度 (Storage Temperature)	-40℃~+125℃		
冷却方式 (Cooling)	加装散热器或强制风冷	Attach Heatsink or Forced Convection	
过温保护 (Thermal Shutdown Range)	100℃~110℃	基板温度 (Baseplate Temperature)	
平均故障间隔时间 (MTBF)	2 × 10 <sup>5</sup> h	MIL-HDBK-217	
重量 (Weight)	80g		

注: 除非另有说明, 指标一般在标称输入电压、满载和 25℃ 基板温度下测得。

Note: All specifications are typical at nominal input, full load at 25℃ baseplate temperature unless otherwise stated.

